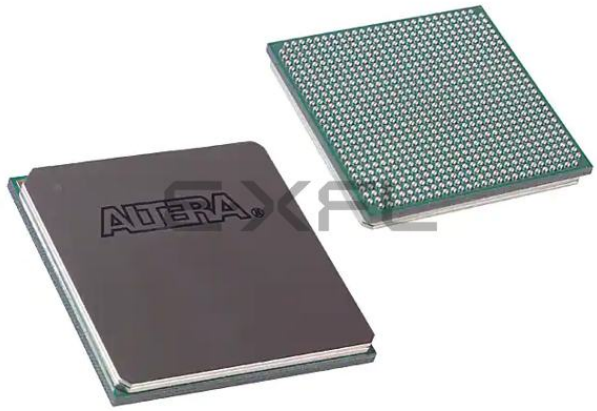

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Details	
Product Status	Active
Number of LABs/CLBs	3491
Number of Logic Elements/Cells	55856
Total RAM Bits	2396160
Number of I/O	374
Number of Gates	-
Voltage - Supply	0.97V ~ 1.03V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	780-BGA
Supplier Device Package	780-FBGA (29x29)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep4ce55f29c9l

Cyclone IV Device Family Speed Grades

Table 1–5 lists the Cyclone IV GX devices speed grades.

Table 1–5. Speed Grades for the Cyclone IV GX Device Family

Device	F169	F324	F484	F672	F896
EP4CGX15	C6, C7, C8, I7	—	—	—	—
EP4CGX22	C6, C7, C8, I7	C6, C7, C8, I7	—	—	—
EP4CGX30	C6, C7, C8, I7	C6, C7, C8, I7	C6, C7, C8, I7	—	—
EP4CGX50	—	—	C6, C7, C8, I7	C6, C7, C8, I7	—
EP4CGX75	—	—	C6, C7, C8, I7	C6, C7, C8, I7	—
EP4CGX110	—	—	C7, C8, I7	C7, C8, I7	C7, C8, I7
EP4CGX150	—	—	C7, C8, I7	C7, C8, I7	C7, C8, I7

Table 1–6 lists the Cyclone IV E devices speed grades.

Table 1–6. Speed Grades for the Cyclone IV E Device Family *(1), (2)*

Device	E144	M164	M256	U256	F256	F324	U484	F484	F780
EP4CE6	C8L, C9L, I8L C6, C7, C8, I7, A7	—	—	I7N	C8L, C9L, I8L C6, C7, C8, I7, A7	—	—	—	—
EP4CE10	C8L, C9L, I8L C6, C7, C8, I7, A7	—	—	I7N	C8L, C9L, I8L C6, C7, C8, I7, A7	—	—	—	—
EP4CE15	C8L, C9L, I8L C6, C7, C8, I7	I7N	C7N, I7N	I7N	C8L, C9L, I8L C6, C7, C8, I7, A7	—	—	C8L, C9L, I8L C6, C7, C8, I7, A7	—
EP4CE22	C8L, C9L, I8L C6, C7, C8, I7, A7	—	—	I7N	C8L, C9L, I8L C6, C7, C8, I7, A7	—	—	—	—
EP4CE30	—	—	—	—	—	A7N	—	C8L, C9L, I8L C6, C7, C8, I7, A7	C8L, C9L, I8L C6, C7, C8, I7
EP4CE40	—	—	—	—	—	A7N	I7N	C8L, C9L, I8L C6, C7, C8, I7, A7	C8L, C9L, I8L C6, C7, C8, I7
EP4CE55	—	—	—	—	—	—	I7N	C8L, C9L, I8L C6, C7, C8, I7	C8L, C9L, I8L C6, C7, C8, I7
EP4CE75	—	—	—	—	—	—	I7N	C8L, C9L, I8L C6, C7, C8, I7	C8L, C9L, I8L C6, C7, C8, I7
EP4CE115	—	—	—	—	—	—	—	C8L, C9L, I8L C7, C8, I7	C8L, C9L, I8L C7, C8, I7

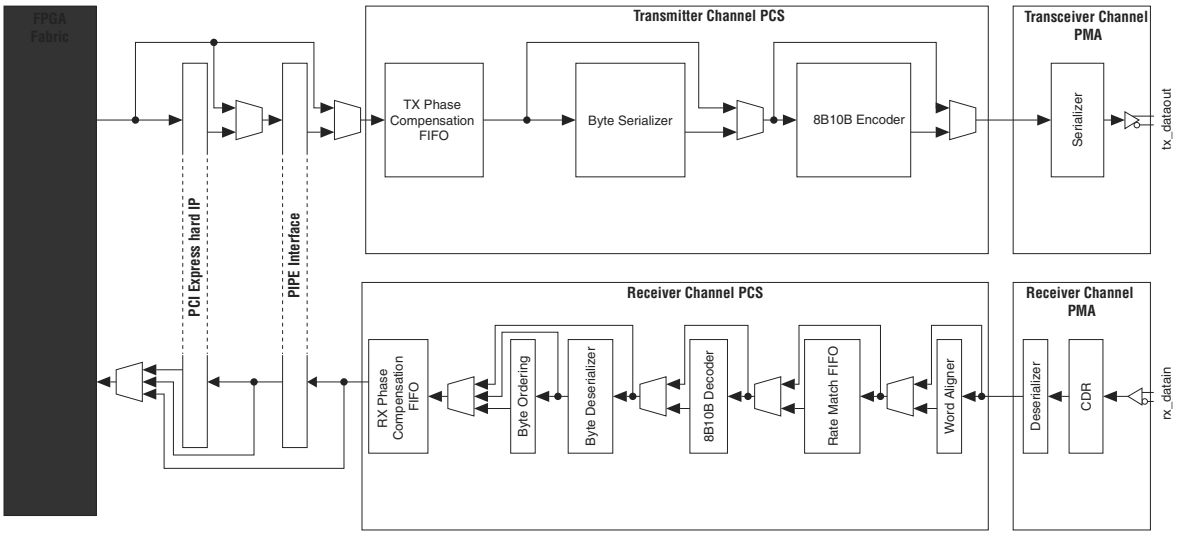
Notes to Table 1–6:

(1) C8L, C9L, and I8L speed grades are applicable for the 1.0-V core voltage.

(2) C6, C7, C8, I7, and A7 speed grades are applicable for the 1.2-V core voltage.

Figure 1–1 shows the structure of the Cyclone IV GX transceiver.

Figure 1–1. Transceiver Channel for the Cyclone IV GX Device



For more information, refer to the *Cyclone IV Transceivers Architecture* chapter.

Hard IP for PCI Express (Cyclone IV GX Devices Only)

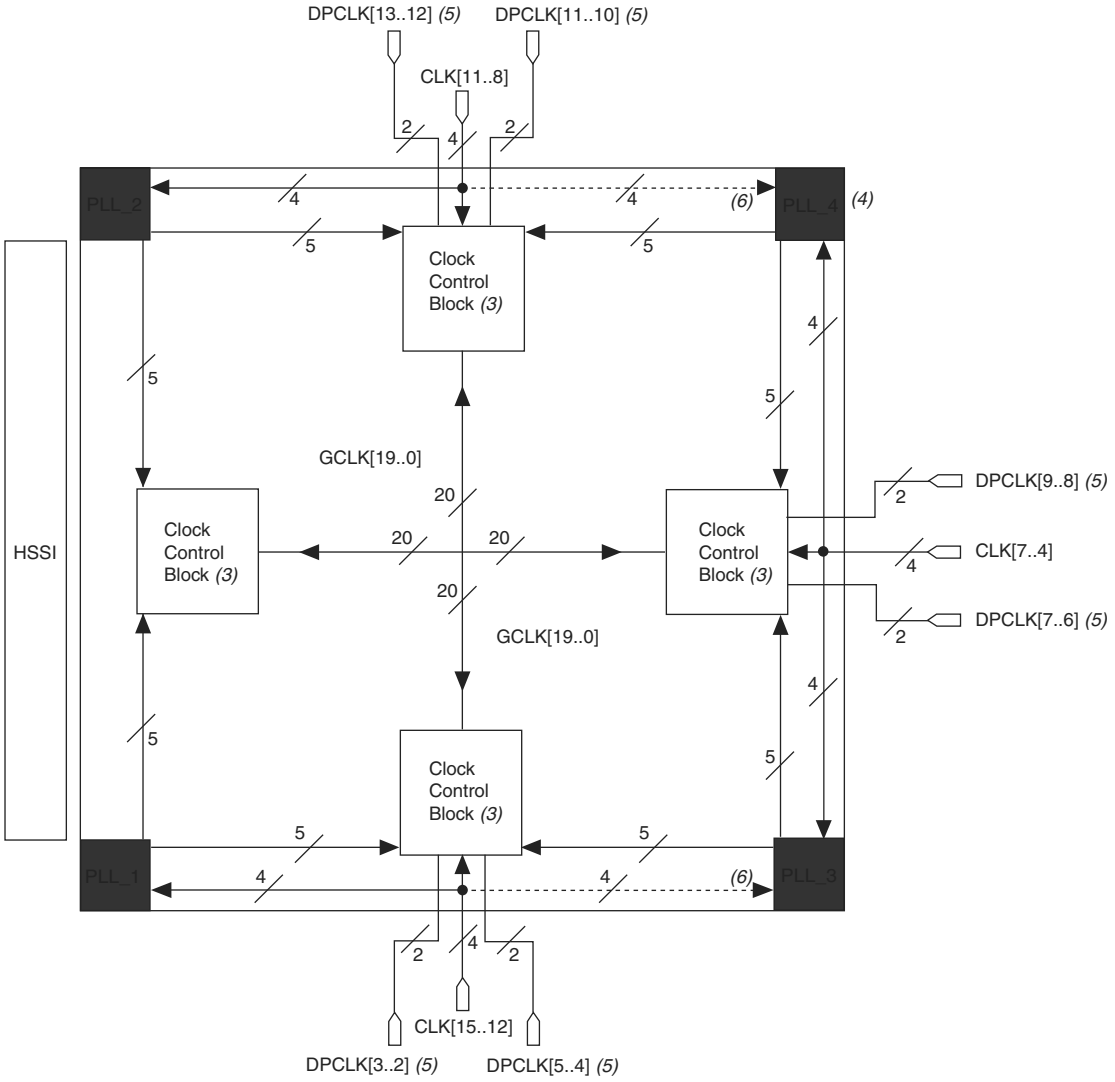
Cyclone IV GX devices incorporate a single hard IP block for ×1, ×2, or ×4 PCIe (PIPE) in each device. This hard IP block is a complete PCIe (PIPE) protocol solution that implements the PHY-MAC layer, Data Link Layer, and Transaction Layer functionality. The hard IP for the PCIe (PIPE) block supports root-port and end-point configurations. This pre-verified hard IP block reduces risk, design time, timing closure, and verification. You can configure the block with the Quartus II software's PCI Express Compiler, which guides you through the process step by step.

For more information, refer to the *PCI Express Compiler User Guide*.

GCLK Network Clock Source Generation

Figure 5–2, Figure 5–3, and Figure 5–4 on page 5–14 show the Cyclone IV PLLs, clock inputs, and clock control block location for different Cyclone IV device densities.

Figure 5–2. Clock Networks and Clock Control Block Locations in EP4CGX15, EP4CGX22, and EP4CGX30 Devices *(1), (2)*



Notes to Figure 5–2:

(1) The clock networks and clock control block locations apply to all EP4CGX15, EP4CGX22, and EP4CGX30 devices except EP4CGX30 device in F484 package.

(2) PLL_1 and PLL_2 are multipurpose PLLs while PLL_3 and PLL_4 are general purpose PLLs.

(3) There are five clock control blocks on each side.

(4) PLL_4 is only available in EP4CGX22 and EP4CGX30 devices in F324 package.

(5) The EP4CGX15 device has two DPCLK pins on three sides of the device: DPCLK2 and DPCLK5 on bottom side, DPCLK7 and DPCLK8 on the right side, DPCLK10 and DPCLK13 on the top side of device.

(6) Dedicated clock pins can feed into this PLL. However, these paths are not fully compensated.

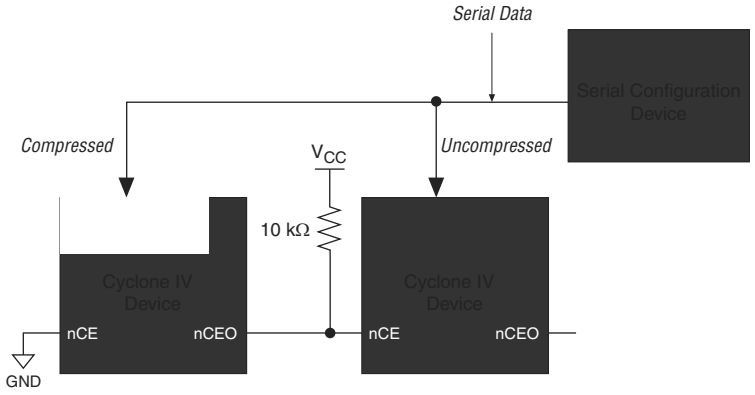
3. Click the **Configuration** tab.
4. Turn on **Generate compressed bitstreams**.
5. Click **OK**.
6. In the **Settings** dialog box, click **OK**.

You can enable compression when creating programming files from the **Convert Programming Files** dialog box. To enable compression, perform the following steps:

1. On the File menu, click **Convert Programming Files**.
2. Under **Output programming file**, select your desired file type from the **Programming file type** list.
3. If you select **Programmer Object File (.pof)**, you must specify the configuration device in the **Configuration device** list.
4. Under **Input files to convert**, select **SOF Data**.
5. Click **Add File** to browse to the Cyclone IV device SRAM object files (**.sof)**.
6. In the **Convert Programming Files** dialog box, select the **.pof** you added to **SOF Data** and click **Properties**.
7. In the **SOF File Properties** dialog box, turn on the **Compression** option.

When multiple Cyclone IV devices are cascaded, you can selectively enable the compression feature for each device in the chain. Figure 8–1 shows a chain of two Cyclone IV devices. The first device has compression enabled and receives compressed bitstream from the configuration device. The second device has the compression feature disabled and receives uncompressed data. You can generate programming files for this setup in the **Convert Programming Files** dialog box.

Figure 8–1. Compressed and Uncompressed Configuration Data in the Same Configuration File



Configuration Requirement

This section describes Cyclone IV device configuration requirement and includes the following topics:

- "Power-On Reset (POR) Circuit" on page 8–4
- "Configuration File Size" on page 8–4
- "Power Up" on page 8–6

During device configuration, Cyclone IV E devices read configuration data using the parallel interface and configure their SRAM cells. This scheme is referred to as the AP configuration scheme because the device controls the configuration interface. This scheme contrasts with the FPP configuration scheme, where an external host controls the interface.

AP Configuration Supported Flash Memories

The AP configuration controller in Cyclone IV E devices is designed to interface with two industry-standard flash families—the Micron P30 Parallel NOR flash family and the Micron P33 Parallel NOR flash family. Unlike serial configuration devices, both of the flash families supported in AP configuration scheme are designed to interface with microprocessors. By configuring from an industry standard microprocessor flash which allows access to the flash after entering user mode, the AP configuration scheme allows you to combine configuration data and user data (microprocessor boot code) on the same flash memory.

The Micron P30 flash family and the P33 flash family support a continuous synchronous burst read mode at 40 MHz DCLK frequency for reading data from the flash. Additionally, the Micron P30 and P33 flash families have identical pin-out and adopt similar protocols for data access.

Cyclone IV E devices use a 40-MHz oscillator for the AP configuration scheme. The oscillator is the same oscillator used in the Cyclone IV E AS configuration scheme.

Table 8–10 lists the supported families of the commodity parallel flash for the AP configuration scheme.

Table 8–10. Supported Commodity Flash for AP Configuration Scheme for Cyclone IV E Devices *(1)*

Flash Memory Density	Micron P30 Flash Family *(2)*	Micron P33 Flash Family *(3)*
64 Mbit	✓	✓
128 Mbit	✓	✓
256 Mbit	✓	✓

Notes to Table 8–10:

(1) The AP configuration scheme only supports flash memory speed grades of 40 MHz and above.
(2) 3.3- , 3.0-, 2.5-, and 1.8-V I/O options are supported for the Micron P30 flash family.
(3) 3.3-, 3.0- and 2.5-V I/O options are supported for the Micron P33 flash family.

Configuring Cyclone IV E devices from the Micron P30 and P33 family 512-Mbit flash memory is possible, but you must properly drive the extra address and FLASH_nCE pins as required by these flash memories.

To check for supported speed grades and package options, refer to the respective flash datasheets.

The AP configuration scheme in Cyclone IV E devices supports flash speed grades of 40 MHz and above. However, AP configuration for all these speed grades must be capped at 40 MHz. The advantage of faster speed grades is realized when your design in the Cyclone IV E devices accesses flash memory in user mode.

Table 8–13. FPP Timing Parameters for Cyclone IV Devices (Part 2 of 2)

Symbol	Parameter	Minimum		Maximum		Unit
		Cyclone IV (1)	Cyclone IV E (2)	Cyclone IV (1)	Cyclone IV E (2)	
t_{ST2CK}	nSTATUS high to first rising edge of DCLK	2		—		µs
t_{DH}	Data hold time after rising edge on DCLK	0		—		ns
t_{CD2UM}	CONF_DONE high to user mode (5)	300		650		µs
t_{CD2CU}	CONF_DONE high to CLKUSR enabled	4 × maximum DCLK period		—		—
t_{CD2UMC}	CONF_DONE high to user mode with **CLKUSR** option on	t_{CD2CU} + (3,192 × CLKUSR period)		—		—
t_{DSU}	Data setup time before rising edge on DCLK	5	8	—	—	ns
t_{CH}	DCLK high time	3.2	6.4	—	—	ns
t_{CL}	DCLK low time	3.2	6.4	—	—	ns
t_{CLK}	DCLK period	7.5	15	—	—	ns
f_{MAX}	DCLK frequency (6)	—	—	133	66	MHz

Notes to Table 8–13:

(1) Applicable for Cyclone IV GX and Cyclone IV E with 1.2-V core voltage.
(2) Applicable for Cyclone IV E with 1.0-V core voltage.
(3) This value is applicable if you do not delay configuration by extending the nCONFIG or nSTATUS low pulse width.
(4) This value is applicable if you do not delay configuration by externally holding the nSTATUS low.
(5) The minimum and maximum numbers apply only if you choose the internal oscillator as the clock source for starting the device.
(6) Cyclone IV E devices with 1.0-V core voltage have slower F_{MAX} when compared with Cyclone IV GX devices with 1.2-V core voltage.

JTAG Configuration

JTAG has developed a specification for boundary-scan testing (BST). The BST architecture offers the capability to efficiently test components on PCBs with tight lead spacing. The BST architecture can test pin connections without using physical test probes and capture functional data while a device is normally operating. You can also use the JTAG circuitry to shift configuration data into the device. The Quartus II software automatically generates **.sof** for JTAG configuration with a download cable in the Quartus II software Programmer.

For more information about the JTAG boundary-scan testing, refer to the *JTAG Boundary-Scan Testing for Cyclone IV Devices* chapter.

Device Configuration Pins

Table 8–18 through Table 8–21 describe the connections and functionality of all the configuration related pins on Cyclone IV devices. Table 8–18 and Table 8–19 list the device pin configuration for the Cyclone IV GX and Cyclone IV E, respectively.

Table 8–18. Configuration Pin Summary for Cyclone IV GX Devices

Bank	Description	Input/Output	Dedicated	Powered By	Configuration Mode
8	Data[4:2]	Input	—	V_{CCIO}	FPP
3	Data[7:5]	Input	—	V_{CCIO}	FPP
9	nCSO (2)	Output	—	V_{CCIO}	AS
3	CRC_ERROR	Output	—	V_{CCIO}/Pull-up (1)	Optional, all modes
9	DATA[0] (2)	Input	Yes	V_{CCIO}	PS, FPP, AS
9	DATA[1]/ASDO (2)	Input	—	V_{CCIO}	FPP
		Output		V_{CCIO}	AS
3	INIT_DONE	Output	—	Pull-up	Optional, all modes
3	nSTATUS	Bidirectional	Yes	Pull-up	All modes
9	nCE	Input	Yes	V_{CCIO}	All modes
9	DCLK (2)	Input	Yes	V_{CCIO}	PS, FPP
		Output		V_{CCIO}	AS
3	CONF_DONE	Bidirectional	Yes	Pull-up	All modes
9	TDI	Input	Yes	V_{CCIO}	JTAG
9	TMS	Input	Yes	V_{CCIO}	JTAG
9	TCK	Input	Yes	V_{CCIO}	JTAG
9	nCONFIG	Input	Yes	V_{CCIO}	All modes
8	CLKUSR	Input	—	V_{CCIO}	Optional
3	nCEO	Output	—	V_{CCIO}	Optional, all modes
3	MSEL	Input	Yes	V_{CCINT}	All modes
9	TDO	Output	Yes	V_{CCIO}	JTAG
6	DEV_OE	Input	—	V_{CCIO}	Optional
6	DEV_CLRn	Input	—	V_{CCIO}	Optional

Notes to Table 8–18:

(1) The CRC_ERROR pin is a dedicated open-drain output or an optional user I/O pin. Active high signal indicates that the error detection circuit has detected errors in the configuration SRAM bits. This pin is optional and is used when the CRC error detection circuit is enabled in the Quartus II software from the **Error Detection CRC** tab of the **Device and Pin Options** dialog box. When using this pin, connect it to an external 10-kΩ pull-up resistor to an acceptable voltage that satisfies the input voltage of the receiving device.

(2) To tri-state AS configuration pins in the AS configuration scheme, turn on the **Enable input tri-state on active configuration pins in user mode** option from the **Device and Pin Options** dialog box. This tri-states DCLK, nCSO, Data[0], and Data[1]/ASDO pins. Dual-purpose pins settings for these pins are ignored. To set these pins to different settings, turn off the **Enable input tri-state on active configuration pins in user mode** option and set the desired setting from the Dual-purpose Pins Setting menu.

Table 8–19. Configuration Pin Summary for Cyclone IV E Devices (Part 1 of 3)

Bank	Description	Input/Output	Dedicated	Powered By	Configuration Mode
1	nCSO (1) FLASH_nCE (2)	Output	—	V_{CCIO}	AS, AP
6	CRC_ERROR (3)	Output	—	V_{CCIO}/Pull-up (4)	Optional, all modes

Table 8–28. Document Revision History (Part 2 of 2)

Date	Version	Changes
July 2010	1.2	Updated for the Quartus II software 10.0 release: ■ Updated "Power-On Reset (POR) Circuit", "Configuration and JTAG Pin I/O Requirements", and "Reset" sections. ■ Updated Figure 8–10. ■ Updated Table 8–16 and Table 8–17.
February 2010	1.1	Updated for the Quartus II software 9.1 SP1 release: ■ Added "Overriding the Internal Oscillator" and "AP Configuration (Supported Flash Memories)" sections. ■ Updated "JTAG Instructions" section. ■ Added Table 8–6. ■ Updated Table 8–2, Table 8–3, Table 8–4, Table 8–6, Table 8–11, Table 8–13, Table 8–14, Table 8–15, and Table 8–18. ■ Updated Figure 8–4, Figure 8–5, Figure 8–6, Figure 8–13, Figure 8–14, Figure 8–15, Figure 8–17, Figure 8–18, Figure 8–23, Figure 8–24, Figure 8–25, Figure 8–26, Figure 8–27, Figure 8–28, and Figure 8–29.
November 2009	1.0	Initial release.

Table 11–1. Power Supply Descriptions for the Cyclone IV GX Devices (Part 2 of 2)

Power Supply Pin	Nominal Voltage Level (V)	Description
VCCL_GXB	1.2	Transceiver PMA and auxiliary power supply

Notes to Table 11–1:

(1) You must power up VCCA even if the phase-locked loop (PLL) is not used.

(2) I/O banks 3, 8, and 9 contain configuration pins. You can only power up the V_{CCIO} level of I/O banks 3 and 9 to 1.5 V, 1.8 V, 2.5 V, 3.0 V, or 3.3 V. For Fast Passive Parallel (FPP) configuration mode, you must power up the V_{CCIO} level of I/O bank 8 to 1.5 V, 1.8 V, 2.5 V, 3.0 V, or 3.3 V.

(3) All device packages of EP4CGX15, EP4CGX22, and device package F169 and F324 of EP4CGX30 devices have two VCC_CLKIN dedicated clock input I/O located at Banks 3A and 8A. Device package F484 of EP4CGX30, all device packages of EP4CGX50, EP4CGX75, EP4CGX110, and EP4CGX150 devices have four VCC_CLKIN dedicated clock input I/O bank located at banks 3A, 3B, 8A, and 8B.

(4) You must set VCC_CLKIN to 2.5V if the CLKIN is used as a high-speed serial interface (HSSI) transceiver refclk. When not used as a transceiver refclk, VCC_CLKIN supports 1.2 V/ 1.5 V/ 1.8 V/ 2.5 V/ 3.0 V/ 3.3V voltages.

Table 11–2. Power Supply Descriptions for the Cyclone IV E Devices

Power Supply Pin	Nominal Voltage Level (V)	Description
VCCINT	1.0, 1.2	Core voltage power supply
VCCA *(1)*	2.5	PLL analog power supply
VCCD_PLL	1.0, 1.2	PLL digital power supply
VCCIO *(2)*	1.2, 1.5, 1.8, 2.5, 3.0, 3.3	I/O banks power supply

Notes to Table 11–2:

(1) You must power up VCCA even if the PLL is not used.

(2) I/O banks 1, 6, 7, and 8 contain configuration pins.

Hot-Socketing Specifications

Cyclone IV devices are hot-socketing compliant without the need for any external components or special design requirements. Hot-socketing support in Cyclone IV devices has the following advantages:

- You can drive the device before power up without damaging the device.
- I/O pins remain tri-stated during power up. The device does not drive out before or during power-up. Therefore, it does not affect other buses in operation.

Devices Driven Before Power-Up

You can drive signals into regular Cyclone IV E I/O pins and transceiver Cyclone IV GX I/O pins before or during power up or power down without damaging the device. Cyclone IV devices support any power-up or power-down sequence to simplify system-level designs.

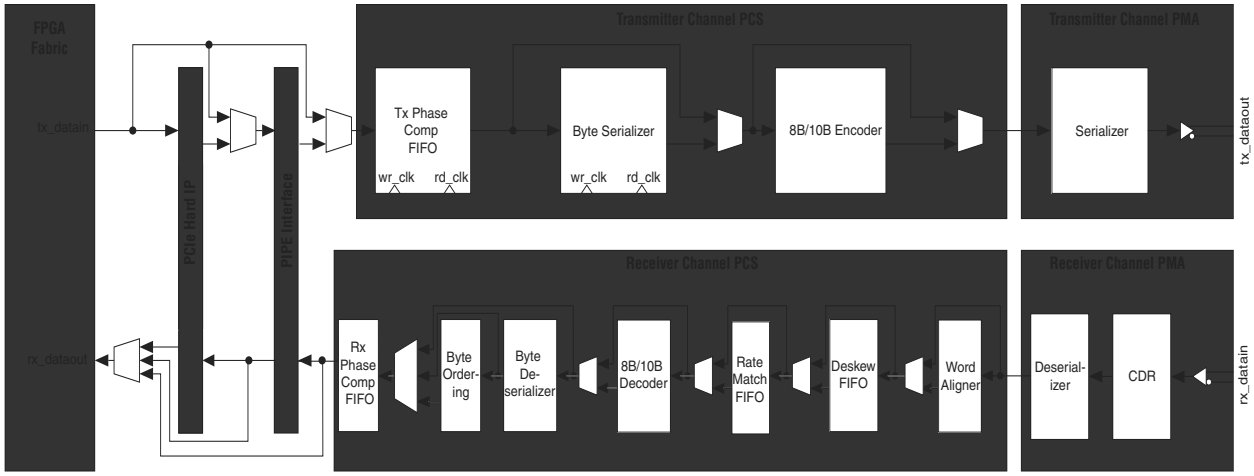
I/O Pins Remain Tri-stated During Power-Up

The output buffers of Cyclone IV devices are turned off during system power up or power down. Cyclone IV devices do not drive out until the device is configured and working in recommended operating conditions. The I/O pins are tri-stated until the device enters user mode.

Architectural Overview

Figure 1–3 shows the Cyclone IV GX transceiver channel datapath.

Figure 1–3. Transceiver Channel Datapath for Cyclone IV GX Devices



Each transceiver channel consists of a transmitter and a receiver datapath. Each datapath is further structured into the following:

- Physical media attachment (PMA)—includes analog circuitry for I/O buffers, clock data recovery (CDR), serializer/deserializer (SERDES), and programmable pre-emphasis and equalization to optimize serial data channel performance.
- Physical coding sublayer (PCS)—includes hard logic implementation of digital functionality within the transceiver that is compliant with supported protocols.

Outbound parallel data from the FPGA fabric flows through the transmitter PCS and PMA, is transmitted as serial data. Received inbound serial data flows through the receiver PMA and PCS into the FPGA fabric. The transceiver supports the following interface widths:

- FPGA fabric-transceiver PCS—8, 10, 16, or 20 bits
- PMA-PCS—8 or 10 bits

The transceiver channel interfaces through the PIPE when configured for PCIe protocol implementation. The PIPE is compliant with version 2.00 of the *PHY Interface for the PCI Express Architecture* specification.

Figure 1–35 shows the datapath clocking in the transmitter and receiver operation mode with the rate match FIFO. The receiver datapath clocking in configuration without the rate match FIFO is identical to Figure 1–34.

In configuration with the rate match FIFO, the CDR unit in the receiver channel recovers the clock from received serial data and generates the high-speed recovered clock for the deserializer, and low-speed recovered clock for forwarding to the receiver PCS. The low-speed recovered clock feeds to the following blocks in the receiver PCS:

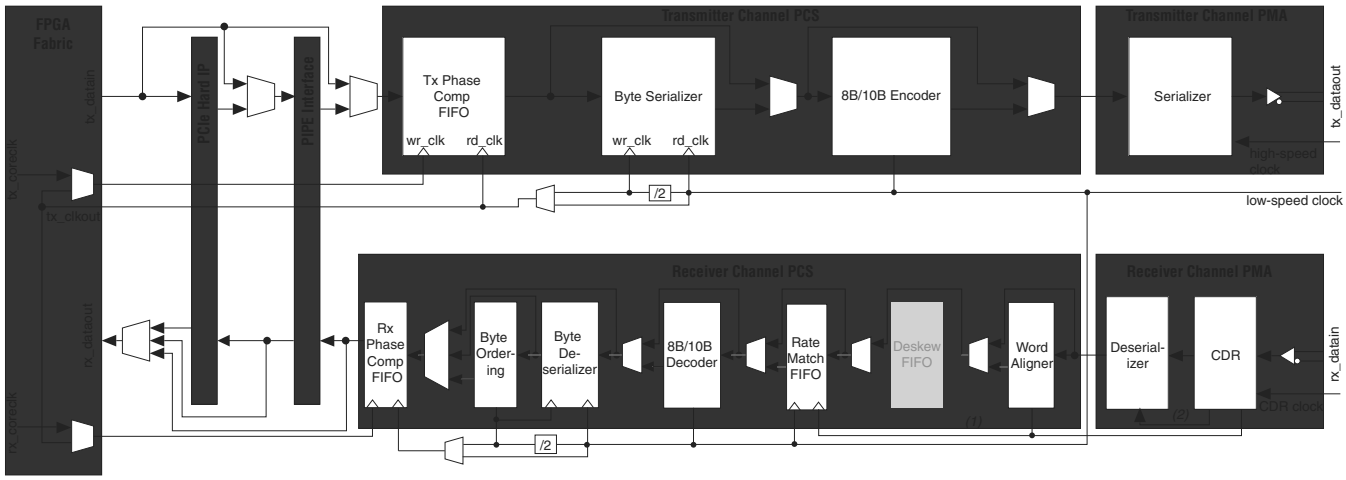
- word aligner
- write clock of rate match FIFO

The low-speed clock that is used in the transmitter PCS datapath feeds the following blocks in the receiver PCS:

- read clock of rate match FIFO
- 8B/10B decoder
- write clock of byte deserializer
- byte ordering
- write clock of RX phase compensation FIFO

When the byte deserializer is enabled, the low-speed clock frequency is halved before feeding into the write clock of RX phase compensation FIFO. The low-speed clock is available in the FPGA fabric as `tx_clkout` port, which can be used in the FPGA fabric to send transmitter data and control signals, and capture receiver data and status signals.

Figure 1–35. Transmitter and Receiver Datapath Clocking with Rate Match FIFO in Non-Bonded Channel Configuration



Notes to Figure 1–35:

(1) Low-speed recovered clock.

(2) High-speed recovered clock.

Table 1–11. FPGA Fabric-Transceiver Interface Clocks (Part 2 of 2)

Clock Name	Clock Description	Interface Direction
cal_blk_clk (2)	Transceiver calibration block clock	FPGA fabric to transceiver

Notes to Table 1–11:

(1) Offset cancellation process that is executed after power cycle requires `reconfig_clk` clock. The `reconfig_clk` must be driven with a free-running clock and not derived from the transceiver blocks.

(2) For the supported clock frequency range, refer to the *Cyclone IV Device Data Sheet*.

In the transmitter datapath, TX phase compensation FIFO forms the FPGA fabric-transmitter interface. Data and control signals for the transmitter are clocked with the FIFO write clock. The FIFO write clock supports automatic clock selection by the Quartus II software (depending on channel configuration), or user-specified clock from `tx_coreclk` port. Table 1–12 details the automatic TX phase compensation FIFO write clock selection by the Quartus II software.

The Quartus II software assumes automatic clock selection for TX phase compensation FIFO write clock if you do not enable the `tx_coreclk` port.

Table 1–12. Automatic TX Phase Compensation FIFO Write Clock Selection

Channel Configuration	Quartus II Selection
Non-bonded	`tx_clkout` clock feeds the FIFO write clock. `tx_clkout` is forwarded through the transmitter channel from low-speed clock, which also feeds the FIFO read clock.
Bonded	`coreclkout` clock feeds the FIFO write clock for the bonded channels. `coreclkout` clock is the common bonded low-speed clock, which also feeds the FIFO read clock in the bonded channels.

When using user-specified clock option, ensure that the clock feeding `tx_coreclk` port has 0 ppm difference with the TX phase compensation FIFO read clock.

In the receiver datapath, RX phase compensation FIFO forms the receiver-FPGA fabric interface. Data and status signals from the receiver are clocked with the FIFO read clock. The FIFO read clock supports automatic clock selection by the Quartus II software (depending on channel configuration), or user-specified clock from `rx_coreclk` port. Table 1–13 details the automatic RX phase compensation FIFO read clock selection by the Quartus II software.

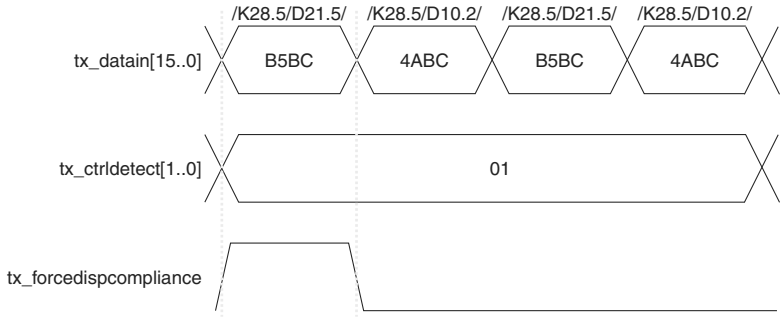
The Quartus II software assumes automatic clock selection for RX phase compensation FIFO read clock if you do not enable the `rx_coreclk` port.

Table 1–13. Automatic RX Phase Compensation FIFO Read Clock Selection (Part 1 of 2)

Channel Configuration		Quartus II Selection
Non-bonded	With rate match FIFO (1)	`tx_clkout` clock feeds the FIFO read clock. `tx_clkout` is forwarded through the receiver channel from low-speed clock, which also feeds the FIFO write clock and transmitter PCS.
	Without rate match FIFO	`rx_clkout` clock feeds the FIFO read clock. `rx_clkout` is forwarded through the receiver channel from low-speed recovered clock, which also feeds the FIFO write clock.

The compliance pattern is a repeating sequence of the four code groups: /K28.5/; /D21.5/; /K28.5/; /D10.2/. Figure 1–53 shows the compliance pattern transmission where the `tx_forcedispcompliance` port must be asserted in the same parallel clock cycle as /K28.5/D21.5/ of the compliance pattern on `tx_datain[15..0]` port.

Figure 1–53. Compliance Pattern Transmission Support in PCI Express (PIPE) Mode



Reset Requirement

Cyclone IV GX devices meets the PCIe reset time requirement from device power up to the link active state with the configuration schemes listed in Table 1–17.

Table 1–18. Electrical Idle Inference Conditions

Device	Configuration Scheme	Configuration Time (ms)
EP4CGX15	Passive serial (PS)	51
EP4CGX22	PS	92
EP4CGX30 (1)	PS	92
EP4CGX50	Fast passive parallel (FPP)	41
EP4CGX75	FPP	41
EP4CGX110	FPP	70
EP4CGX150	FPP	70

Note to Table 1–18:

(1) EP4CGX30 device in F484 package fulfills the PCIe reset time requirement using FPP configuration scheme with configuration time of 41 ms.

GIGE Mode

GIGE mode provides the transceiver channel datapath configuration for GbE (specifically the 1000 Base-X physical layer device (PHY) standard) protocol implementation. The Cyclone IV GX transceiver provides the PMA and the following PCS functions as defined in the IEEE 802.3 specification for 1000 Base-X PHY:

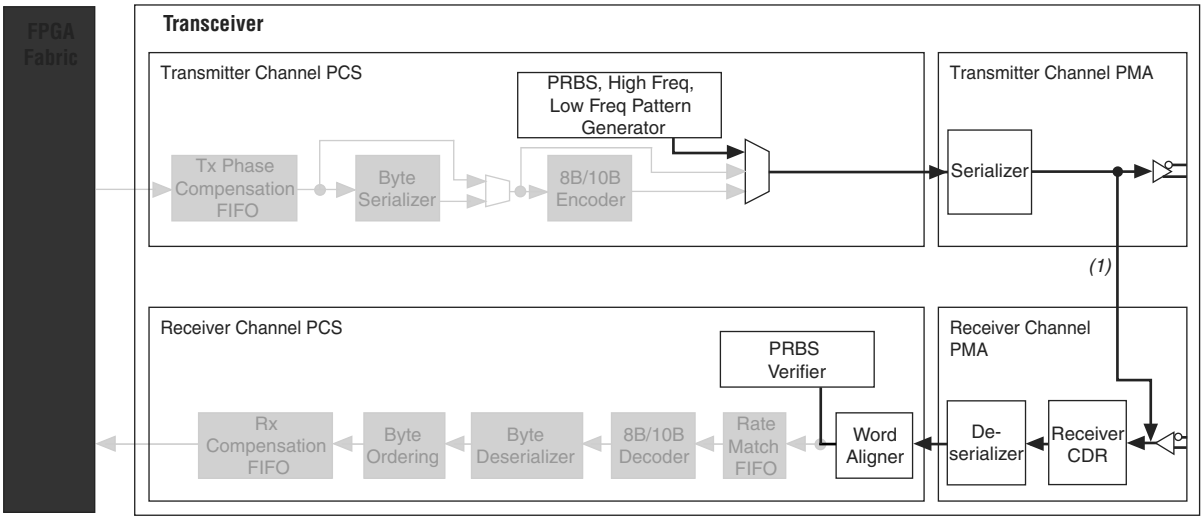
- 8B/10B encoding and decoding
- synchronization

If you enabled the auto-negotiation state machine in the FPGA core with the rate match FIFO, refer to “Clock Frequency Compensation” on page 1–63.

PRBS

Figure 1–74 shows the datapath for the PRBS, high and low frequency pattern test modes. The pattern generator is located in TX PCS before the serializer, and PRBS pattern verifier located in RX PCS after the word aligner.

Figure 1–74. PRBS Pattern Test Mode Datapath



Note to Figure 1–74:

(1) Serial loopback path is optional and can be enabled for the PRBS verifier to check the PRBS pattern

Table 1–25 lists the supported PRBS, high and low frequency patterns, and corresponding channel settings. The PRBS pattern repeats after completing an iteration. The number of bits a PRBS X pattern sends before repeating the pattern is $2^{(X-1)}$ bits.

Table 1–25. PRBS, High and Low Frequency Patterns, and Channel Settings (Part 1 of 2)

Patterns	Polynomial	8-bit Channel Width				10-bit Channel Width			
		Channel Width of 8 bits (1)	Word Alignment Pattern	Maximum Data Rate (Gbps) for F324 and Smaller Packages	Maximum Data Rate (Gbps) for F484 and Larger Packages	Channel Width of 10-bits (1)	Word Alignment Pattern	Maximum Data Rate (Gbps) for F324 and Smaller Packages	Maximum Data Rate (Gbps) for F484 and Larger Packages
PRBS 7	$X^7 + X^6 + 1$	Y	16'h3040	2.0	2.5	N	—	—	—
PRBS 8	$X^8 + X^7 + 1$	Y	16'hFF5A	2.0	2.5	N	—	—	—
PRBS 10	$X^{10} + X^7 + 1$	N	—	—	—	Y	10'h3FF	2.5	3.125
PRBS 23	$X^{23} + X^{18} + 1$	Y	16'hFFFF	2.0	2.5	N	—	—	—
High frequency (2)	1010101010	Y	—	2.0	2.5	Y	—	2.5	3.125

Table 1–27. Receiver Ports in ALTGX Megafunction for Cyclone IV GX (Part 3 of 3)

Block	Port Name	Input/ Output	Clock Domain	Description
RX PCS	rx_coreclk	Output	Clock signal	Optional read clock port for the RX phase compensation FIFO.
	rx_phase_comp_fifo_error	Output	Synchronous to `tx_clkout` (non-bonded modes) or `coreclkout` (bonded modes)	RX phase compensation FIFO full or empty indicator. ■ A high level indicates FIFO is either full or empty.
	rx_bitslipboundaryselectout	Output	Asynchronous signal.	Indicate the number of bits slipped in the word aligner configured in manual alignment mode. ■ Values range from 0 to 9.
RX PMA	rx_datain	Input	N/A	Receiver serial data input port.
	rx_freqlocked	Output	Asynchronous signal	Receiver CDR lock state indicator ■ A high level indicates the CDR is in LTD state. ■ A low level indicates the CDR is in LTR state.
	rx_locktodata	Input	Asynchronous signal	Receiver CDR LTD state control signal ■ A high level forces the CDR to LTD state ■ When deasserted, the receiver CDR lock state depends on the `rx_locktorefclk` signal level.
	rx_locktorefclk	Input	Asynchronous signal	Receiver CDR LTR state control signal. ■ The `rx_locktorefclk` and `rx_locktodata` signals control whether the receiver CDR states as follows: [`rx_locktodata:rx_locktorefclk`] ■ 2'b00—receiver CDR is in automatic lock mode ■ 2b'01—receiver CDR is in manual lock mode (LTR state) ■ 2b'1x—receiver CDR is in manual lock mode (LTD state)
	rx_signaldetect	Output	Asynchronous signal	Signal threshold detect indicator. ■ Available in Basic mode when 8B/10B encoder/decoder is used, and in PIPE mode. ■ A high level indicates that the signal present at the receiver input buffer is above the programmed signal detection threshold value.
	rx_recovclkout	Output	Clock signal	CDR low-speed recovered clock ■ Only available in the GIGE mode for applications such as Synchronous Ethernet.

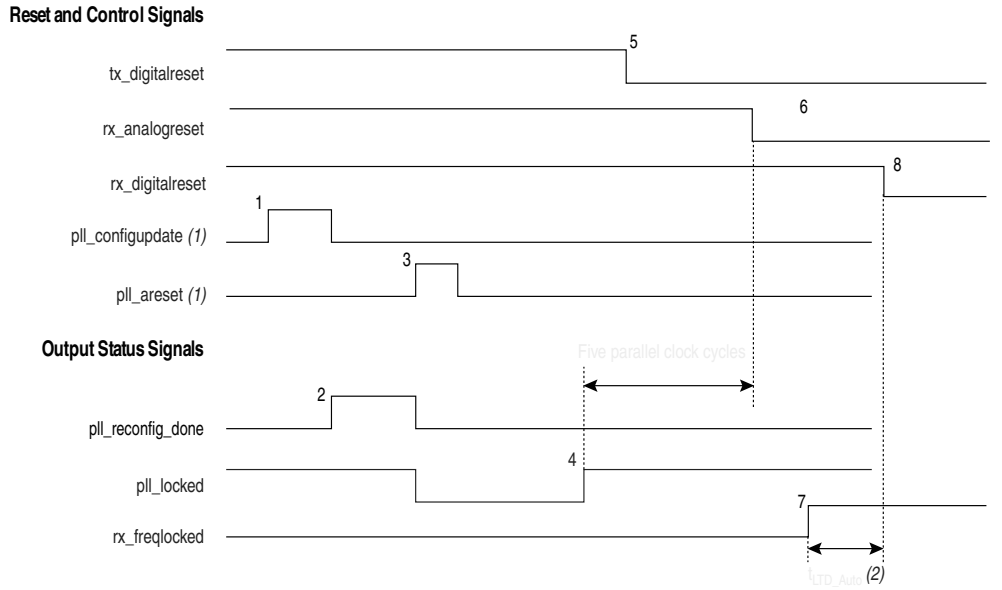
Dynamic Reconfiguration Reset Sequences

When using dynamic reconfiguration in data rate divisions in PLL reconfiguration or channel reconfiguration mode, use the following reset sequences.

Reset Sequence in PLL Reconfiguration Mode

Use the example reset sequence shown in Figure 2–11 when you use the PLL dynamic reconfiguration controller to change the data rate of the transceiver channel. In this example, PLL dynamic reconfiguration is used to dynamically reconfigure the data rate of the transceiver channel configured in Basic ×1 mode with the receiver CDR in automatic lock mode.

Figure 2–11. Reset Sequence When Using the PLL Dynamic Reconfiguration Controller to Change the Data Rate of the Transceiver Channel



Notes to Figure 2–11:

(1) The `pll_configupdate` and `pll_areset` signals are driven by the ALTPLL_RECONFIG megafunction. For more information, refer to *AN 609: Implementing Dynamic Reconfiguration in Cyclone IV GX Devices* and the *Cyclone IV Dynamic Reconfiguration* chapter.

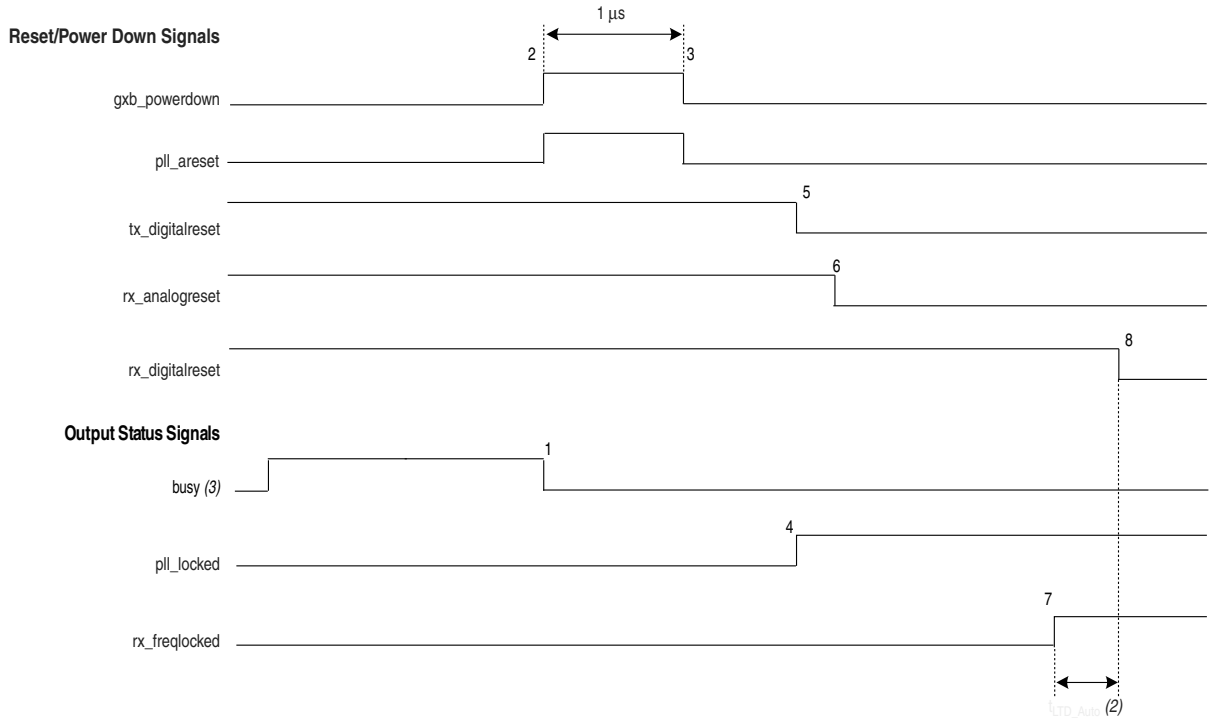
(2) For t_{LTD_Auto} duration, refer to the *Cyclone IV Device Datasheet* chapter.

As shown in Figure 2–11, perform the following reset procedure when using the PLL dynamic reconfiguration controller to change the configuration of the PLLs in the transmitter channel:

1. Assert the `tx_digitalreset`, `rx_analogreset`, and `rx_digitalreset` signals. The `pll_configupdate` signal is asserted (marker 1) by the ALTPLL_RECONFIG megafunction after the final data bit is sent out. The `pll_reconfig_done` signal is asserted (marker 2) to inform the ALTPLL_RECONFIG megafunction that the scan chain process is completed. The ALTPLL_RECONFIG megafunction then asserts the `pll_areset` signal (marker 3) to reset the transceiver PLL.

The deassertion of the busy signal indicates proper completion of the offset cancellation process on the receiver channel.

Figure 2–13. Sample Reset Sequence of a Receiver and Transmitter Channels-Receiver CDR in Automatic Lock Mode with the Optional gxb_powerdown Signal (1)



Notes to Figure 2–13:

(1) The gxb_powerdown signal must not be asserted during the offset cancellation sequence.

(2) For t_{LTD_Auto} duration, refer to the *Cyclone IV Device Datasheet* chapter.

(3) The busy signal is asserted and deasserted only during initial power up when offset cancellation occurs. In subsequent reset sequences, the busy signal is asserted and deasserted only if there is a read or write operation to the ALTGX_RECONFIG megafunction.

Simulation Requirements

The following are simulation requirements:

- The gxb_powerdown port is optional. In simulation, if the gxb_powerdown port is not instantiated, you must assert the tx_digitalreset, rx_digitalreset, and rx_analogreset signals appropriately for correct simulation behavior.
- If the gxb_powerdown port is instantiated, and the other reset signals are not used, you must assert the gxb_powerdown signal for at least 1 µs for correct simulation behavior.
- You can deassert the rx_digitalreset signal immediately after the rx_freqlocked signal goes high to reduce the simulation run time. It is not necessary to wait for t_{LTD_Auto} (as suggested in the actual reset sequence).
- The busy signal is deasserted after about 20 parallel reconfig_clk clock cycles in order to reduce simulation run time. For silicon behavior in hardware, you can follow the reset sequences described in the previous pages.

1. Cyclone IV Device Datasheet

CYIV-53001-2.1

This chapter describes the electrical and switching characteristics for Cyclone® IV devices. Electrical characteristics include operating conditions and power consumption. Switching characteristics include transceiver specifications, core, and periphery performance. This chapter also describes I/O timing, including programmable I/O element (IOE) delay and programmable output buffer delay.

This chapter includes the following sections:

Operating Conditions

When Cyclone IV devices are implemented in a system, they are rated according to a set of defined parameters. To maintain the highest possible performance and reliability of Cyclone IV devices, you must consider the operating requirements described in this chapter.

Cyclone IV devices are offered in commercial, industrial, extended industrial and, automotive grades. Cyclone IV E devices offer –6 (fastest), –7, –8, –8L, and –9L speed grades for commercial devices, –8L speed grades for industrial devices, and –7 speed grade for extended industrial and automotive devices. Cyclone IV GX devices offer –6 (fastest), –7, and –8 speed grades for commercial devices and –7 speed grade for industrial devices.

For more information about the supported speed grades for respective Cyclone IV devices, refer to the *Cyclone IV FPGA Device Family Overview* chapter.

Cyclone IV E devices are offered in core voltages of 1.0 and 1.2 V. Cyclone IV E devices with a core voltage of 1.0 V have an 'L' prefix attached to the speed grade.

In this chapter, a prefix associated with the operating temperature range is attached to the speed grades; commercial with a "C" prefix, industrial with an "I" prefix, and automotive with an "A" prefix. Therefore, commercial devices are indicated as C6, C7, C8, C8L, or C9L per respective speed grade. Industrial devices are indicated as I7, I8, or I8L. Automotive devices are indicated as A7.

Internal Weak Pull-Up and Weak Pull-Down Resistor

Table 1–12 lists the weak pull-up and pull-down resistor values for Cyclone IV devices.

Table 1–12. Internal Weak Pull-Up and Weak Pull-Down Resistor Values for Cyclone IV Devices *(1)*

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{\_PU}$	Value of the I/O pin pull-up resistor before and during configuration, as well as user mode if you enable the programmable pull-up resistor option	V_{CCIO} = 3.3 V ± 5% *(2), (3)*	7	25	41	kΩ
		V_{CCIO} = 3.0 V ± 5% *(2), (3)*	7	28	47	kΩ
		V_{CCIO} = 2.5 V ± 5% *(2), (3)*	8	35	61	kΩ
		V_{CCIO} = 1.8 V ± 5% *(2), (3)*	10	57	108	kΩ
		V_{CCIO} = 1.5 V ± 5% *(2), (3)*	13	82	163	kΩ
		V_{CCIO} = 1.2 V ± 5% *(2), (3)*	19	143	351	kΩ
$R_{\_PD}$	Value of the I/O pin pull-down resistor before and during configuration	V_{CCIO} = 3.3 V ± 5% *(4)*	6	19	30	kΩ
		V_{CCIO} = 3.0 V ± 5% *(4)*	6	22	36	kΩ
		V_{CCIO} = 2.5 V ± 5% *(4)*	6	25	43	kΩ
		V_{CCIO} = 1.8 V ± 5% *(4)*	7	35	71	kΩ
		V_{CCIO} = 1.5 V ± 5% *(4)*	8	50	112	kΩ

Notes to Table 1–12:

(1) All I/O pins have an option to enable weak pull-up except the configuration, test, and JTAG pins. The weak pull-down feature is only available for JTAG TCK.

(2) Pin pull-up resistance values may be lower if an external source drives the pin higher than V_{CCIO}.

(3) $R_{\_PU} = (V_{CCIO} – V_I)/I_{R\_PU}$
Minimum condition: –40°C; $V_{CCIO} = V_{CC}$ + 5%, $V_I = V_{CC}$ + 5% – 50 mV;
Typical condition: 25°C; $V_{CCIO} = V_{CC}$, V_I = 0 V;
Maximum condition: 100°C; $V_{CCIO} = V_{CC}$ – 5%, V_I = 0 V; in which V_I refers to the input voltage at the I/O pin.

(4) $R_{\_PD} = V_I/I_{R\_PD}$
Minimum condition: –40°C; $V_{CCIO} = V_{CC}$ + 5%, V_I = 50 mV;
Typical condition: 25°C; $V_{CCIO} = V_{CC}$, $V_I = V_{CC}$ – 5%;
Maximum condition: 100°C; $V_{CCIO} = V_{CC}$ – 5%, $V_I = V_{CC}$ – 5%; in which V_I refers to the input voltage at the I/O pin.

Hot-Socketing

Table 1–13 lists the hot-socketing specifications for Cyclone IV devices.

Table 1–13. Hot-Socketing Specifications for Cyclone IV Devices

Symbol	Parameter	Maximum
$I_{IOPIN(DC)}$	DC current per I/O pin	300 µA
$I_{IOPIN(AC)}$	AC current per I/O pin	8 mA *(1)*
$I_{XCVRTX(DC)}$	DC current per transceiver TX pin	100 mA
$I_{XCVRRX(DC)}$	DC current per transceiver RX pin	50 mA

Note to Table 1–13:

(1) The I/O ramp rate is 10 ns or more. For ramp rates faster than 10 ns, |IIOPIN| = C dv/dt, in which C is the I/O pin capacitance and dv/dt is the slew rate.

☞ During hot-socketing, the I/O pin capacitance is less than 15 pF and the clock pin capacitance is less than 20 pF.